

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	13	Giri.in. and chip with module	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2004/11/16 12:31
S2	12	("5633532" "5710071" "5834334" "5985693" "6010951" "6281042" "6281452" "6291268" "6304232" "6347037" "6376917" "6424034").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/11/16 12:33
S3	95	multi\$1chip near3 module same carrier same (ic chip semiconductor) and opposite near3 surface	USPAT; USOCR; EPO; JPO	OR	ON	2004/11/16 12:42
S4	36	S3 and frame	USPAT; USOCR; EPO; JPO	OR	ON	2004/11/16 12:38
S5	3	multi\$1chip near3 module same thin\$1film same carrier same (ic chip semiconductor) and (both opposite) near3 surface	USPAT; USOCR; EPO; JPO	OR	ON	2004/11/16 12:44
S6	11	multi\$1chip near3 module same carrier same (ic chip semiconductor) and (both opposite) near3 surface and (remov\$3 strip\$4) near3 carrier	USPAT; USOCR; EPO; JPO	OR	ON	2004/11/16 12:45
S7	12	("5633532" "5710071" "5834334" "5985693" "6010951" "6281042" "6281452" "6291268" "6304232" "6347037" "6376917" "6424034").PN.	USPAT; EPO; JPO	OR	ON	2004/11/22 14:39
S8	78	(thin\$1film multi\$1layer) near3 (structure board substrate) same (carrier plate holder) same (frame damp) same (ic chip semiconductor)	USPAT; EPO; JPO	OR	ON	2004/11/22 15:39
S9	51	(thin\$1film multi\$1layer) near3 (structure board substrate) with (carrier plate holder) and (frame damp spacer) same (ic chip semiconductor) and (remov\$4 detach\$3) with (carrier plate holder)	USPAT; EPO; JPO	OR	ON	2004/11/22 16:18
S10	165	(thin\$1film multi\$1layer) near3 (structure board substrate) and (temporary remov\$4 detach\$4) near3 (carrier plate holder) and (frame damp spacer) same (ic chip semiconductor)	USPAT; EPO; JPO	OR	ON	2004/11/22 16:20

S32	130	thin\$1film with (structure substrate board) and (frame plate carrier holder) near4 (temporary remov\$4 detach\$4) and (insulat\$3 dielectric ceramic organic) near4 (frame plate damp ring)	USPAT; EPO; JPO	OR	ON	2004/11/23 12:13
S33	141	thin\$1film with (structure substrate board) and (frame plate carrier holder support\$2) near4 (temporary remov\$4 detach\$4) and (insulat\$3 dielectric ceramic organic) near4 (frame plate dam ring)	USPAT; EPO; JPO	OR	ON	2004/11/23 12:17
S34	75	thin\$1film same (frame plate carrier holder support\$2) near4 (temporary remov\$4 detach\$4) and (insulat\$3 dielectric ceramic organic) near4 (board substrate frame plate)	USPAT; EPO; JPO	OR	ON	2004/11/23 12:23
S35	24	("4812191" "4914814" "5056215" "5060844" "5116459" "5154341" "5170931" "5258236" "5306872" "5338900" "5342713" "5347162" "5368963" "5409157" "5427876" "5464712" "5521032" "5534094" "5534466" "5565286" "5633535" "5700715" "5861666" "5994168").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/11/23 12:20
S36	24	thin\$1film with module and (frame plate carrier holder support\$2) near4 (temporary remov\$4 detach\$4) and (insulat\$3 dielectric ceramic organic) near4 (board substrate frame plate)	USPAT; EPO; JPO	OR	ON	2004/11/23 12:31
S37	1	"6769174".pn.	USPAT; EPO; JPO	OR	ON	2004/11/23 12:31
S38	7	("20020027010" "20020100165" "5218759" "5480503" "5620928" "6130473" "6247229").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/11/23 12:31
S39	109	multi near1 chip near2 (module carier) with frame	USPAT; EPO; JPO	OR	ON	2005/04/18 16:37
S40	15	("5070041" "5268533" "5387815" "5523608" "5729049" "5874773" "5917234" "6020625" "6054755" "6147397" "6191490" "6288904" "6387732" "6396142" "RE37690").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/18 15:57
S41	383	"29"/\$ and multi near1 chip near2 (module carier) and frame	USPAT; EPO; JPO	OR	ON	2005/04/18 16:38
S42	176	"29"/\$ and multi near1 chip near2 (module carier) and frame and thin near2 (film layer substrate)	USPAT; EPO; JPO	OR	ON	2005/04/18 16:38

S43	49	"29"/\$ and multi near1 chip near2 (module carier) and frame and thin near2 (film layer substrate) and temporary	USPAT; EPO; JPO	OR	ON	2005/04/18 16:44
S44	28	"174"/\$ and multi near1 chip near2 (module carier) and frame and thin near2 (film layer substrate) and temporary	USPAT; EPO; JPO	OR	ON	2005/04/18 16:45
S45	36	"361"/\$ and multi near1 chip near2 (module carier) and frame and thin near2 (film layer substrate) and temporary	USPAT; EPO; JPO	OR	ON	2005/04/18 16:46
S46	51	"257"/\$ and multi near1 chip near2 (module carier) and frame and thin near2 (film layer substrate) and temporary	USPAT; EPO; JPO	OR	ON	2005/04/18 16:49
S47	38	"438"/\$ and multi near1 chip near2 (module carier) and frame and thin near2 (film layer substrate) and temporary	USPAT; EPO; JPO	OR	ON	2005/04/18 16:51
S48	41	multi near1 chip near2 (module carier board substrate) and frame and thin near2 (film layer substrate) and temporary near2 (carrier plate support film layer substrate board)	USPAT; EPO; JPO	OR	ON	2005/04/18 16:56
S49	1	multi near1 chip same frame and thin near2 (film layer substrate) and temporary near2 (carrier plate support film layer substrate board)	USPAT; EPO; JPO	OR	ON	2005/04/18 16:57
S50	9	multi near1 chip and frame same thin near2 (film layer substrate) and temporary near2 (carrier plate support film layer substrate board)	USPAT; EPO; JPO	OR	ON	2005/04/18 16:58
S51	131	multi near1 chip and frame same thin near2 (film layer substrate) same (carrier plate support film layer substrate board)	USPAT; EPO; JPO	OR	ON	2005/04/18 16:58

S79	147	multi near2 chip and (film layer plate board substrate carrier) with (strip\$4 peel\$3 remov\$4) and thin near2 film and (opposit\$3 second) near2 surface with (mounting chip)	USPAT; EPO; JPO	OR	ON	2005/04/19 12:51
S80	112	multi near2 chip near2 (module carrier board substrate) and (support\$3 temporary scarificial) near2 (film layer plate board substrate carrier) with (strip\$4 peel\$3 remov\$4)	USPAT; EPO; JPO	OR	ON	2005/04/19 15:56
S81	8	multi near2 chip and (support\$3 temporary scarificial) near2 (film layer plate board substrate carrier) with (strip\$4 peel\$3 remov\$4) and thin near2 film and (insulat\$3 dielectric) near2 (frame stiffener carrier ring)	USPAT; EPO; JPO	OR	ON	2005/04/19 16:04
S82	26	multi near2 chip and (support\$3 temporary scarificial) near2 (film layer plate board substrate carrier) with (strip\$4 peel\$3 remov\$4) and thin near2 film and (frame stiffener)	USPAT; EPO; JPO	OR	ON	2005/04/19 16:09
S83	16	multi near2 chip and (temporary scarificial) near2 (plate board substrate carrier) with (strip\$4 peel\$3 remov\$4) and (frame stiffener)	USPAT; EPO; JPO	OR	ON	2005/04/19 16:12
S84	34	multi near2 chip and (temporary scarificial) with (plate board substrate carrier) with (strip\$4 peel\$3 remov\$4) and (frame stiffener)	USPAT; EPO; JPO	OR	ON	2005/04/19 16:14
S85	250	multi near2 chip and (plate board substrate carrier) with (strip\$4 peel\$3 remov\$4) and (frame stiffener) and thin near2 film	USPAT; EPO; JPO	OR	ON	2005/04/19 16:14
S86	88	S83/\$ and S85	USPAT; EPO; JPO	OR	ON	2005/04/19 16:22
S87	82	"438"/\$ and S85	USPAT; EPO; JPO	OR	ON	2005/04/19 16:29
S88	96	"361"/\$ and S85	USPAT; EPO; JPO	OR	ON	2005/04/19 17:18
S89	17	("5012323" "5241456" "5299094" "5394300" "5396102" "5412538" "5471369" "5661339" "5744862" "5754408" "5798564" "5936305" "5956233" "5977640" "5998865" "6008538" "6072699").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/19 16:31
S90	11	("6160718").URPN.	USPAT	OR	ON	2005/04/19 16:34

S91	16	("5239198" "5430611" "5474458" "5477082" "5521435" "5544017" "5646828" "5744862" "5901041" "6005771" "6072122" "6160718" "6222265" "6274929" "6281042" "6326696").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/19 16:35
S92	5	("5570274" "5744862" "5982026" "6038132" "6160718").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/19 16:37
S93	131	"257"/\$ and S85	USPAT; EPO; JPO	OR	ON	2005/04/19 17:20
S94	5	("5570274" "5744862" "5982026" "6038132" "6160718").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/19 18:01
S95	1578	(peter near2 vo).xp.	USPAT; EPO; JPO	OR	ON	2005/04/19 18:02
S96	20	(peter near2 vo).xp. and multi near2 chip	USPAT; EPO; JPO	OR	ON	2005/04/19 18:04
S97	0	(peter near2 vo).xa. and multi near2 chip	USPAT; EPO; JPO	OR	ON	2005/04/19 18:04
S98	95	(peter near2 vo).xp. and chip and frame	USPAT; EPO; JPO	OR	ON	2005/04/19 18:05